



Product End-of-Life Disassembly Instructions

Product Category: Data Storage Devices

Marketing Name / Model

[List multiple models if applicable.]

DAT160 external SCSI / Q1574X & EB631X (where X = any alphanumeric combination)

DAT160 external USB / Q1581X & EB636X (where X = any alphanumeric combination)

DAT160 external SAS / Q1588X & EB641X (where X = any alphanumeric combination)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants	USB interface cable for the desktop (external) product.	1
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx screwdriver	T-8, T-10, T-15
Crosshead screwdriver	0
Flathead screwdriver	N/A
Knife / Scalpel	N/A

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

ENCLOSURE

3.1.1. Remove the lid by removing 1 x T-8 screw from the rear of the lid (see image 1 below). Use a flathead screwdriver to release the "snap-fit" connectors securing the lid and base to the chassis.

3.1.2. Remove the mechanism: disconnect the 5/12V DC power supply cable, SCSI (or SAS / USB) data connector and SCSI ID address cable. Unscrew 1 x T-15 screw (inside enclosure) and 4 x T-8 screws (underneath enclosure) securing the mechanism plate to the chassis and slide the mechanism (& base plate) out from the front of the enclosure (see image 2 below). Mechanism contains 4 x PCAs > 10 square cm's.

3.1.3. Remove the Power Supply Unit (PSU) lid. Remove 1 x T-10 screw from the front of the chassis (in front of PSU) and slide the PSU cover back towards the rear of the enclosure.

3.1.4. Remove the PSU. Remove 4 x T-10 screws, 1 x from each corner and cut the 2 x tie wraps securing the heat shrink cables to the chassis. The board is > 10 square cm's and contains 1 x electrolytic capacitor > 2.5 cm in height. (see image 3).

3.1.5. Remove the USB interface cable (USB enclosure only). Remove 2 x T-10 screws securing the USB cable assembly to the chassis and pull the cable through. Cable jacket contains brominated flame retardant. (see image 4).

MECHANISM

3.1.6. Remove side panels and the lid by unscrewing 14 x crosshead (CH) screws from each side. (See image 5 below). Remove the lid by removing 1 x CH screw at the rear of the mechanism (See image 6) and 2 x CH screws at the front top of the mechanism (see image 7).

3.1.7. Remove the base and the cartridge assembly (see image 8) and remove 1 x CH screw from the BOM-ASSY. (see image 9)

3.1.8. Unlock and release FFCs and FPCs from the PCA (see image 10).

3.1.13. Unscrew 5 x CH screws from the base of the PCA and remove PCA (> 10 sq cm's). (see images 11 & 12).

3.1.9. Unscrew 3 x CH screws to remove the REC-SW-PWA-ASSY > 10 square cm's. (see image 13).

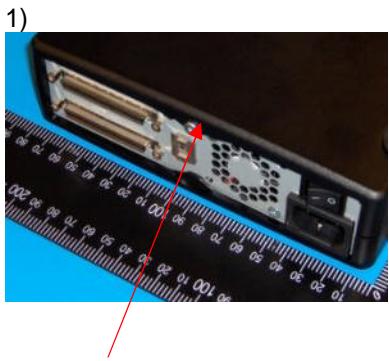
3.1.10. Remove ARM-HOUSING, HC-W-ASSY, ARM-P8-SUB-ASSY, the GUIDE-V-PR, and PR-ASSY from drive to access the MODE-DRIVE-ASSY. (see images 14 and 15)

3.1.11. Unlock FFC connector and release FFC-9pin. Unscrew 6 x CH screws and remove MODE-DRIVE-ASSY. (See image 16).

3.1.12. Cut out the 4 x wires from the mode-drive-assembly and unscrew the 4 x CH screws to release the PWB-MODE-A. (see image 17). PWB-MODE-A is > 10 square cm's.

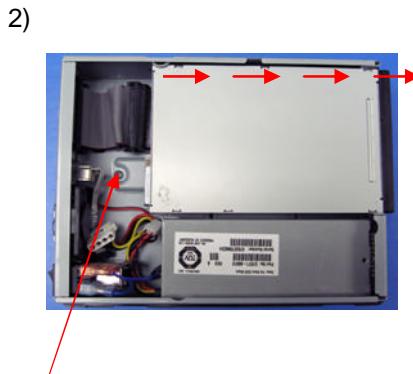
3.1.13 Remove 5 x CH screws to release the P-SUB-CHASSIS, 7 x CH screws to remove the REEL-MOTOR and PWB-MODE-B-ASSY and 3 x CH screws to release the DRUM-ASSY. PWB-MODE-B-ASSY is > 10 square cm's. See image 18

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

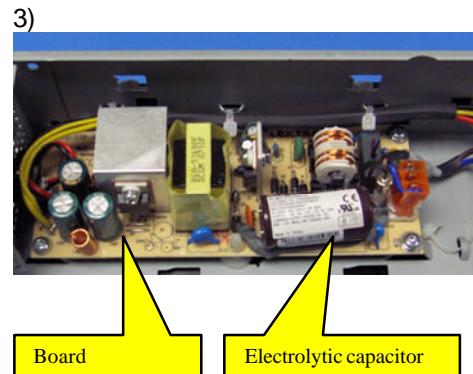


Remove 1 x T-8 screws from rear of lid / chassis. Use a flathead screwdriver to unclip the catches securing the lid to the chassis.

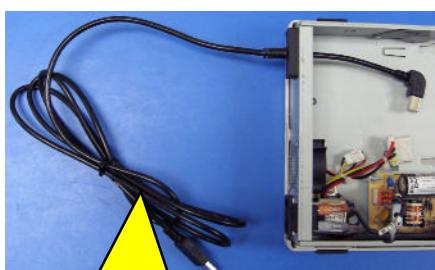
4)



1 x T-15 screw to remove the mechanism. Mechanism & base plate will then slide out in direction of arrows.

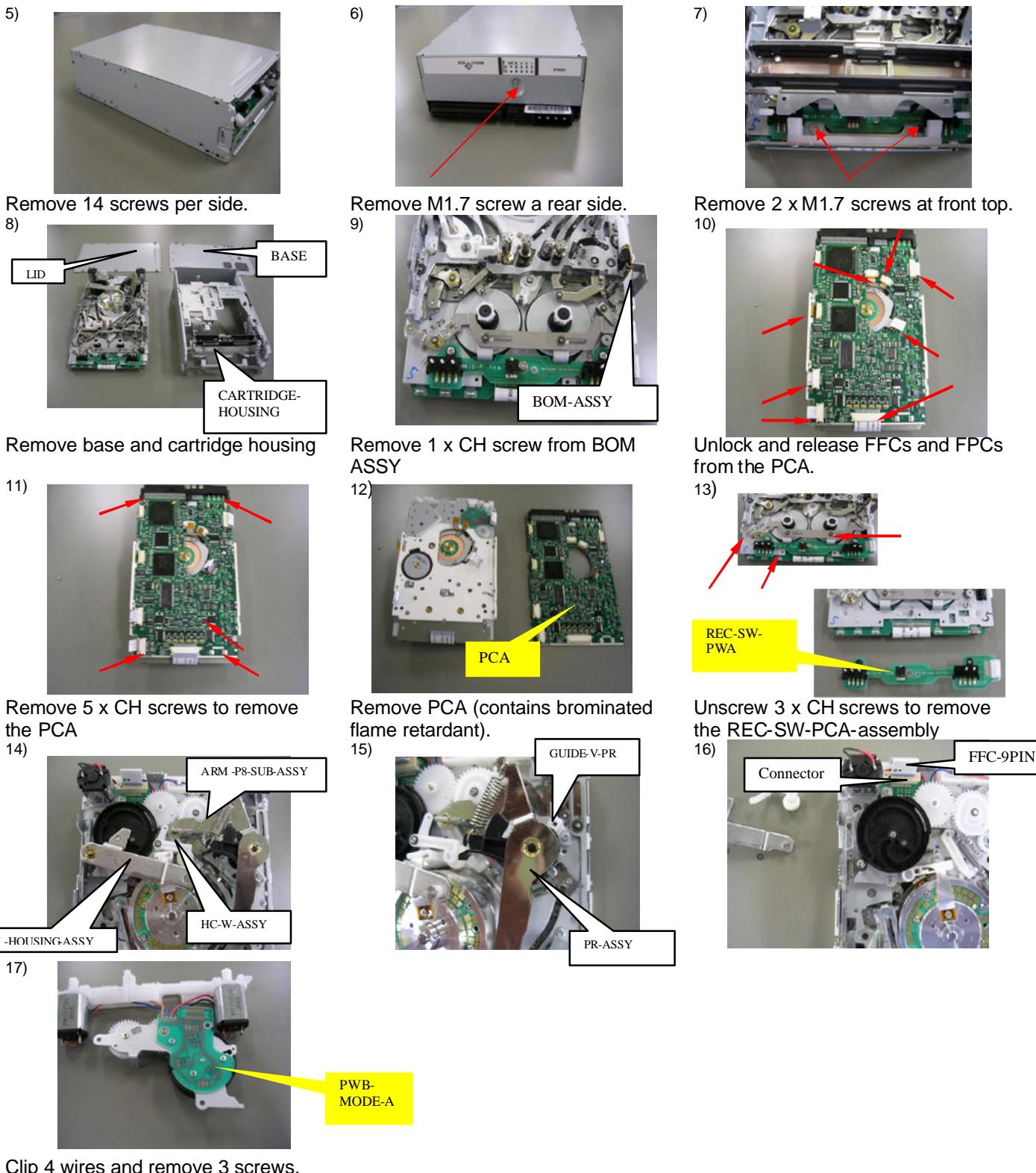


Board > 10 square cm's
1 x electrolytic capacitor > 2.5 cm.

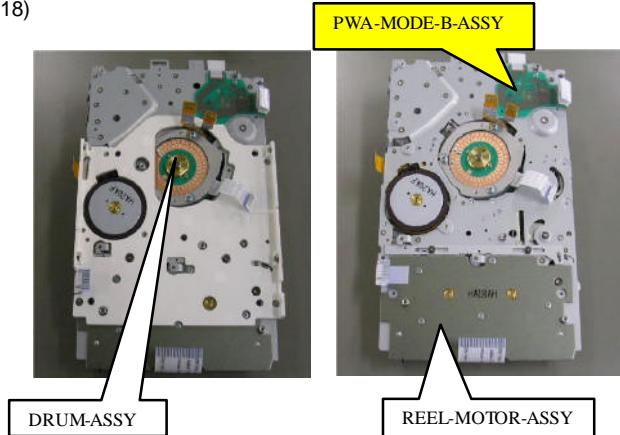


USB cable jacket contains brominated flame retardant

Cable jacket contains brominated FR



18)



Remove PWA-MODE-B-ASSY. > 10 square cm's